CLAIMS

[Claim 1]

A xylylenediamine composition comprising xylylenediamine and bis(methylbenzyl)amine, a content of the bis(methylbenzyl)amine being 0.0005 to 0.1 parts by mass based on 100 parts by mass of the xylylenediamine.

[Claim 2]

The xylylenediamine composition according to claim 1, wherein the xylylenediamine is m-xylylenediamine, p-xylylenediamine, or a mixture thereof.

[Claim 3]

The xylylenediamine composition according to claim 1, wherein the xylylenediamine is m-xylylenediamine.

[Claim 4]

The xylylenediamine composition according to any one of claims 1 to 3, wherein a content of the xylylenediamine is 99.5% by mass or more.

[Claim 5]

The xylylenediamine composition according to any one of claims 1 to 4, which is used for a raw material for polyamide resin.

[Claim 6]

The xylylenediamine composition according to any one of claims 1 to 4, which is used for an epoxy resin curing agent.

[Claim 7]

A method for producing a polyamide resin comprising the steps of introducing a diamine containing xylylenediamine, a dicarboxylic acid, and bis(methylbenzyl)amine in an amount of 0.0005 to 0.1 parts by mass based on 100 parts by mass of the xylylenediamine into a reaction system and performing a polycondensation reaction.

[Claim 8]

The method for producing a polyamide resin according to claim 7, wherein the dicarboxylic acid is at least one selected from an aliphatic dicarboxylic acid having 4 to 20 carbon atoms, terephthalic acid, and isophthalic acid.

[Claim 9]

The method for producing a polyamide resin according to claim 7 or 8, wherein a content of the xylylenediamine in the diamine is 70 mol% or more, and a content of the aliphatic dicarboxylic acid having 4 to 20 carbon atoms in the

dicarboxylic acid is 50 mol% or more.

[Claim 10]

The method for producing a polyamide resin according to claim 8 or 9, wherein the aliphatic dicarboxylic acid having 4 to 20 carbon atoms is at least one selected from adipic acid and sebacic acid.

[Claim 11]

The method for producing a polyamide resin according to any one of claims 7 to 10, wherein the xylylenediamine is m-xylylenediamine, p-xylylenediamine, or a mixture thereof.

[Claim 12]

The method for producing a polyamide resin according to any one of claims 7 to 11, wherein the xylylenediamine is m-xylylenediamine.

[Claim 13]

The method for producing a polyamide resin according to any one of claims 7 to 12, further comprising the step of performing solid-phase polymerization.

CLAIMS

[Claim 1]

A xylylenediamine composition comprising xylylenediamine and bis(methylbenzyl)amine, a content of the bis(methylbenzyl)amine being 0.0005 to 0.1 parts by mass based on 100 parts by mass of the xylylenediamine.

[Claim 2]

The xylylenediamine composition according to claim 1, wherein the xylylenediamine is m-xylylenediamine, p-xylylenediamine, or a mixture thereof.

[Claim 3]

The xylylenediamine composition according to claim 1, wherein the xylylenediamine is m-xylylenediamine.

[Claim 4]

The xylylenediamine composition according to any one of claims 1 to 3, wherein a content of the xylylenediamine is 99.5% by mass or more.

[Claim 5]

The xylylenediamine composition according to any one of claims 1 to 4, which is used for a raw material for polyamide resin.

[Claim 6]

A method for producing a polyamide resin comprising the steps of introducing a diamine containing xylylenediamine, a dicarboxylic acid, and bis(methylbenzyl)amine in an amount of 0.0005 to 0.1 parts by mass based on 100 parts by mass of the xylylenediamine into a reaction system and performing a polycondensation reaction.

[Claim 7]

The method for producing a polyamide resin according to claim 6, wherein the dicarboxylic acid is at least one selected from an aliphatic dicarboxylic acid having 4 to 20 carbon atoms, terephthalic acid, and isophthalic acid.

[Claim 8]

The method for producing a polyamide resin according to claim 6 or 7, wherein a content of the xylylenediamine in the diamine is 70 mol% or more, and a content of the aliphatic dicarboxylic acid having 4 to 20 carbon atoms in the dicarboxylic acid is 50 mol% or more.

[Claim 9]

The method for producing a polyamide resin according to claim 7 or 8, wherein the aliphatic dicarboxylic acid having 4 to 20 carbon atoms is at least one selected from adipic acid and sebacic acid.

[Claim 10]

The method for producing a polyamide resin according to any one of claims 6 to 9, wherein the xylylenediamine is m-xylylenediamine, p-xylylenediamine, or a mixture thereof.

[Claim11]

The method for producing a polyamide resin according to any one of claims 6 to 10, wherein the xylylenediamine is m-xylylenediamine.

[Claim 12]

The method for producing a polyamide resin according to any one of claims 6 to 11, further comprising the step of performing solid-phase polymerization.